



XA-9890
PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Takashi MIWA et al.

Appln. No.: 10/606,891

Group Art Unit: 2824

Filed: June 27, 2003

Examiner: A. Tran

For: STACKED LARGE-SCALE INTEGRATED CIRCUIT (LSI)
SEMICONDUCTOR DEVICE WITH MINIATURIZATION AND THINNING OF
PACKAGE (AS AMENDED)

* * *

RESPONSE

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

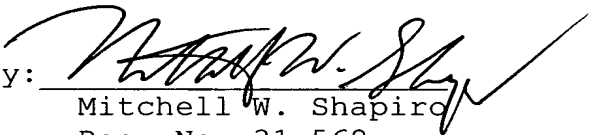
Responsive to the Examiner's request in the
Communication dated September 19, 2005, a reformatted
version of the substitute specification is submitted
herewith. The reformatted version is identical in content
to the previously filed version, except that the spelling
of "Package" has been corrected in the title.

A further action on the merits is respectfully
requested.

The Commissioner is hereby authorized to charge to Deposit Account No. 50-1165 any fees under 37 C.F.R. §§ 1.16 and 1.17 that may be required by this paper and to credit any overpayment to that Account. If any extension of time is required in connection with the filing of this paper and has not been requested separately, such extension is hereby requested.

Respectfully submitted,

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By: 
Mitchell W. Shapiro
Reg. No. 31,568

September 28, 2005